

HITPOINT

SPECIFICATION

PRODUCT TYPE: <u>PMOF-9767NP-46UQ</u>

(RoHS)

DSND	
BY	
CHKD	
BY	
APVD	
BY	

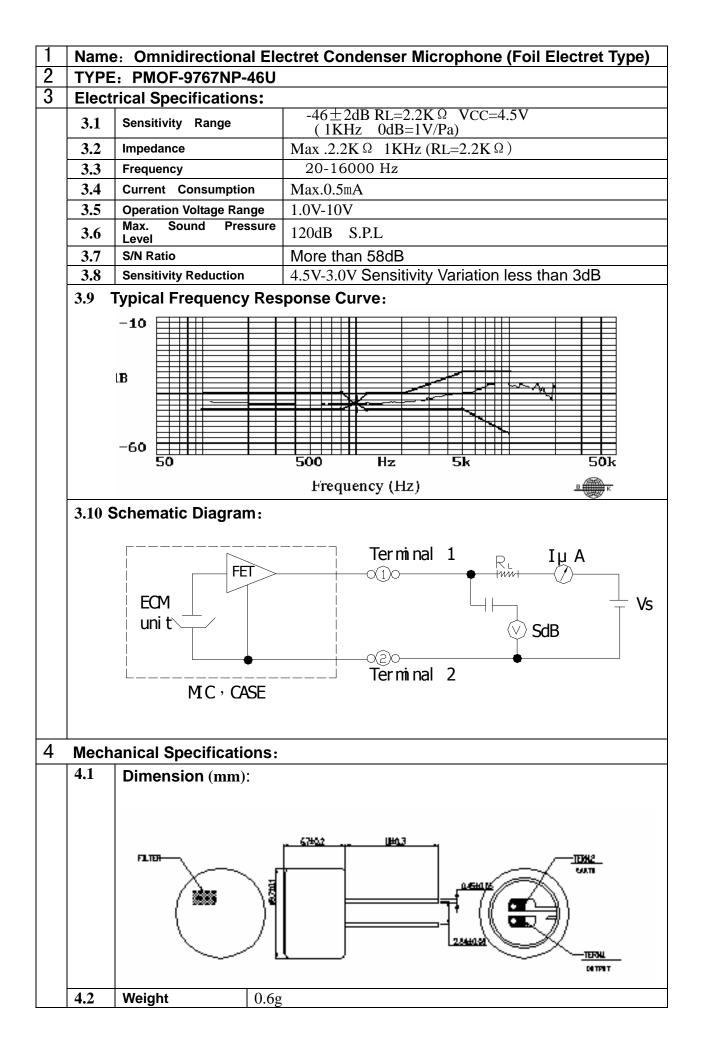
光键股份有限公司

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5.Reliability Tests: After any following tests, the sensitivity of the microphone unit shall not				
change more than ± 3 dB from initial value, and shall keep their initial				
operation and appearance.				
	5.1	Hi-Temp. Test	The microphone unit must be subjected to +70 $^\circ\!\!\mathbb{C}$ for 48	
5.1			Hours, and expose to room temperature for 3 Hours.	
	5.2	Low-Temp. Test	The microphone unit must be subjected to -25 $^\circ\!\!\mathbb{C}$ for 48	
	5.2	ionip: 1001	Hours, and expose to room temperature for 3 Hours.	
	5.3	Humi.&Heat Tes	The microphone unit must be subjected to +40 $^\circ\!$	
			RH-for 48 Hours, and expose to room temp for 3 Hours.	
	F A Humidity Shocking	The microphone unit must be subjected to following		
	5.4	Test	conditions (+45°C 1H-room temp 1H;-10°C 1H-room temp	
			1H) at 5 cycle, and expose to room temp for 3 Hours.	
		Vibration Test	The microphone unit must be subjected to a procedure that after	
	5.5 Vibration lest		vibrating for two hours from each of the two directions with a	
			frequency of 10-55Hz and a 1.52mm-high amplitude.	
	5.6 Dropping Test	The microphone unit must be subjected to a procedure that after		
	5.0		dropping to a slippery marble floor for 5 times from a	
		1-meter-high without package.		
6	Envir	ronmental Condition:		
	6.1			
	6.2			
	6.3 Arbitration condition		Temperature : 20℃±1℃	
			Relative humidity: 63%~67%	
		Air pressure : 86~106Kpa		
7	Notic	Ces:		
ì		All the soldering procedures upon microphones must be completed in a		
7.1 metallic device, the temperature of the soldering iron r		e temperature of the soldering iron must be limited as 310		
	℃ ±20 ℃.			
	7.2 Operators, the solder fixtures and the soldering irons must be star			
	grounded under each soldering process.			